AMENDMENTS TO THE CLAIMS

1.   (Currently amended)   A method of controlling the burning in of at least one I/C chip in a burn in tool, wherein said tool has a device for mounting each chip to be burned in, a power source to supply electrical current individually to burn in each chip, and a monitor for each chip to continuously monitor the temperature value of each chip, comprising the steps of:

continuously monitoring at least one electrical value input to each chip selected from the group of current, voltage and power, and varying the voltage to each chip to maintain at least one of the values at or below a given value.

2.   (Currently amended)   The method of claim 1 wherein the voltage at each chip is varied to maintain the current value below a given value.

3.   (Currently amended)   The method of claim 1 wherein the voltage at each chip is varied to maintain the power value below a given value.

4.   (Currently amended)   The method of claim 1 wherein each device temperature is monitored individually and the voltage to each device is individually varied to maintain the device at a given temperature.

5.   (Currently amended)   The method of claim 1 where there is a heat sink in contact with the ~~device~~chip.

6.   (Currently amended)   The method of claim 5 wherein the ~~device~~chip temperature of each ~~device~~chip is monitored and the temperature of the heat sink is varied to maintain the device temperature at a given value.

7.   (Currently amended)   A burn in tool for burning in at least one I/C chip comprising:

a structure for mounting each chip to be burned in individually;

a power source to supply electrical current individually to burn in each chip;

a structure for continuously monitoring at least one electrical value input to each chip individually selected from the group of current, voltage and power, and

a structure to vary the voltage to maintain at least one of the values of each chip at or below a given value.

8.   (Currently amended)   The tool of claim 7 wherein the voltage is varied to maintain the current value at each chip below a given value.

9   (Currently amended)   The tool of claim 5 wherein the voltage is varied to maintain the power value at each chip below a given value.

10. (Currently amended) The tool of claim 7 including a monitor to continuously monitor the temperature value of each chip individually being burned in and wherein the voltage is varied to maintain the temperature value of each ~~device~~chip individually at a given value.

11. (Currently amended) The tool of claim 7 wherein a heat sink is in contact with each ~~device~~chip.

12. (Currently amended) The tool of claim 7 wherein the tool has a heat sink and temperature monitor for each ~~device~~chip and each heat sink has means to control the temperature of the heat sink, and the temperature control means is varied to maintain the temperature value of each ~~device~~chip at a given value.

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